



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2 $\theta$ 1/2
KPBD-3224SURKCGKC	HYPER RED (InGaAlP)	WATER CLEAR	380	800	20°
	GREEN (InGaAlP)		18	120	

Note:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

## Electrical / Optical Characteristics at T<sub>A</sub>=25°C

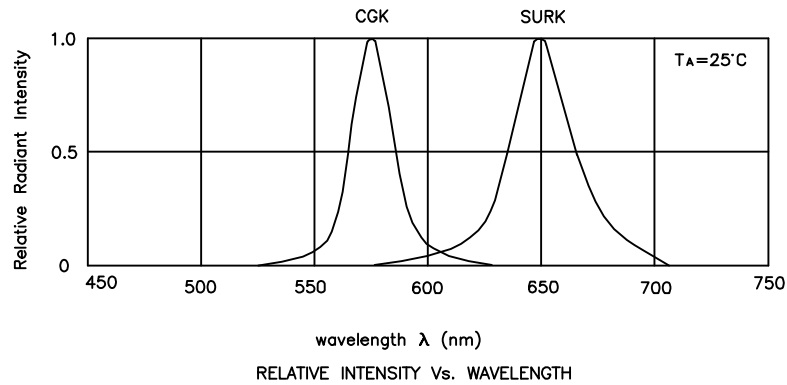
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Hyper Red Green	650 574		nm	I <sub>F</sub> =20mA
$\lambda_D$	Dominant Wavelength	Hyper Red Green	635 570		nm	I <sub>F</sub> =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Red Green	28 20		nm	I <sub>F</sub> =20mA
C	Capacitance	Hyper Red Green	35 15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Hyper Red Green		10 10	uA	V <sub>R</sub> = 5V

## Absolute Maximum Ratings at T<sub>A</sub>=25°C

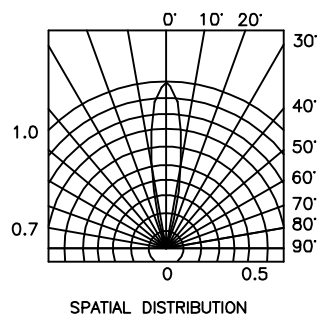
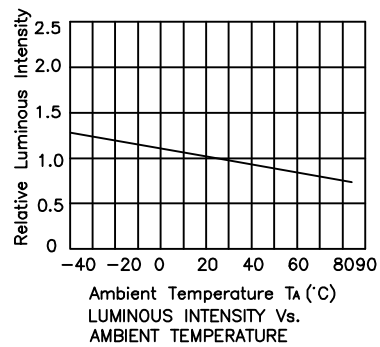
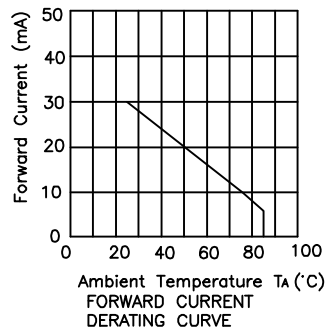
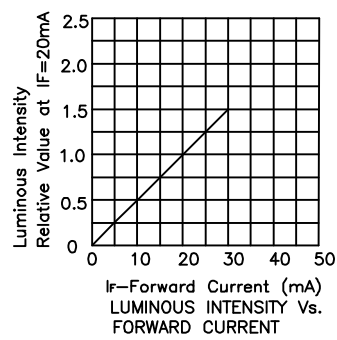
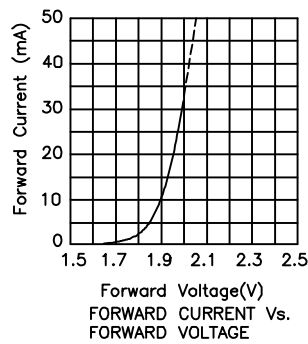
Parameter	Hyper Red	Green	Units
Power dissipation	170	105	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating / storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

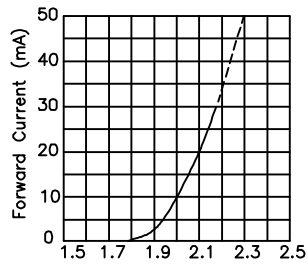


## KPBD-3224SURKCGKC Hyper Red

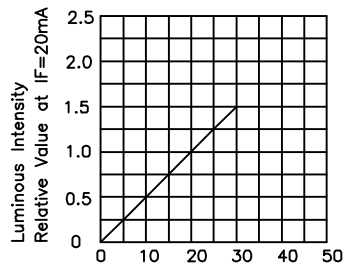


# Kingbright

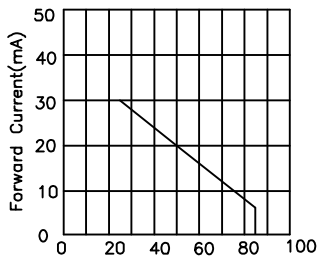
## Green



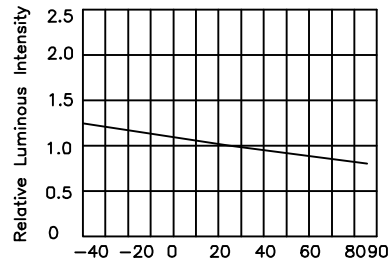
Forward Voltage(V)  
FORWARD CURRENT Vs.  
FORWARD VOLTAGE



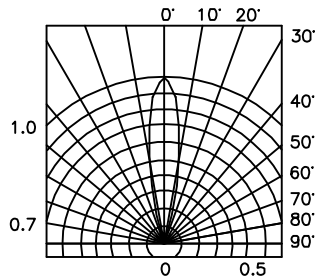
IF-Forward Current (mA)  
LUMINOUS INTENSITY Vs.  
FORWARD CURRENT



Ambient Temperature  $T_a$  (°C)  
FORWARD CURRENT  
DERATING CURVE



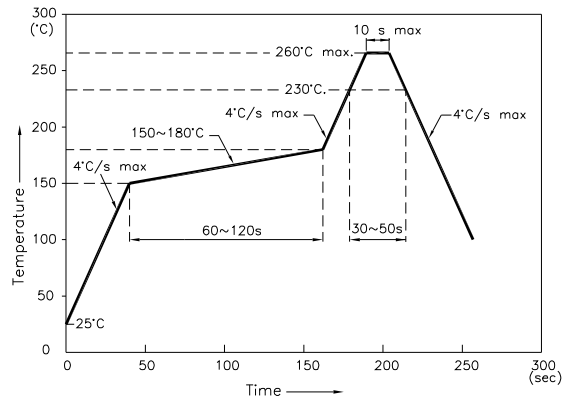
Ambient Temperature  $T_a$  (°C)  
LUMINOUS INTENSITY Vs.  
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

## KPBD-3224SURKCGKC

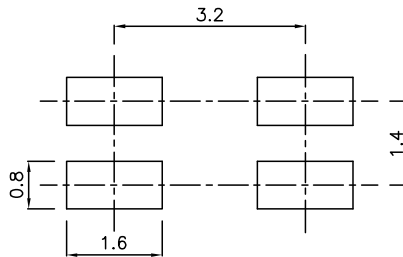
Reflow Soldering Profile For Lead-free SMT Process.



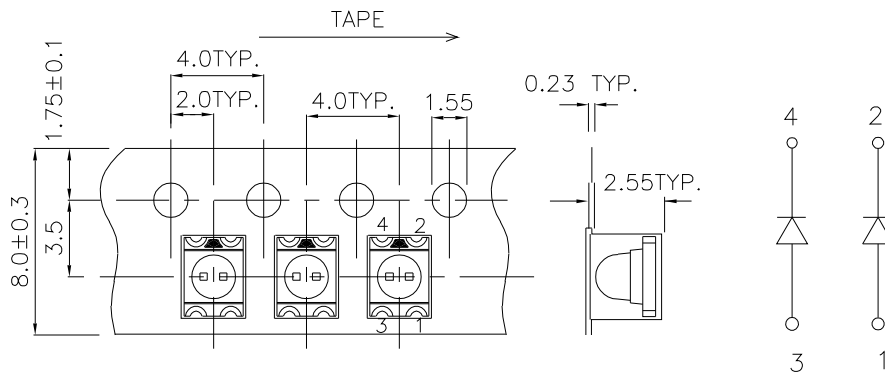
**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)



**Remarks:**

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.